Abstracts

New 3D low loss, wide band microwave interconnection

P. Monfraix, A. Coello Vera, O. Llopis, P. Ulian, S. George, C. Drevon, C. Tronche and J. Graffeuil. "New 3D low loss, wide band microwave interconnection." 1997 MTT-S International Microwave Symposium Digest 3. (1997 Vol. III [MWSYM]): 1551-1554.

This paper describes a new wide band [0; 40 GHz] vertical interconnection approach between two RF homogeneously grounded coplanar lines. It can be considered as two 90/spl deg/ vertical bends transition. Both electromagnetic simulation and measurement demonstrate very good results on the whole frequency range.

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